

LISTING OF THE CLAIMS

This listing of the claims replaces any and all prior versions and listings of claims in the application:

1. **(Currently Amended)** A method of bonding a ceramic material to a manufacturing tool comprising

providing a de-bondable adhesive composition consisting **essentially** of [[a]] **one or more** novolac resins and **one or more** solvents, wherein the **one or more** solvents has a boiling point in the range of about 30°C to about 80°C; placing the adhesive composition onto a surface of the ceramic material;

contacting the manufacturing tool with the adhesive composition on the surface of the ceramic material such that the tool and the ceramic material bond together; and

subjecting the adhesive composition located between the tool and the ceramic material to conditions effective to substantially remove the **one or more** solvents from the adhesive, wherein the ceramic material is used to form sliders for hard disk drive applications.

2. **(Original)** The method according to claim 1, wherein the resist adhesive resin is present in an amount of about 30 wt.% to about 80 wt.%.
3. **(Original)** The method according to claim 1, wherein the resist adhesive resin is present in an amount of about 40 wt.% to about 70 wt.%.
4. **(Original)** The method according to claim 1, wherein the resist adhesive resin is present in an amount of about 55 wt.% to about 65 wt.%.
5. **(Original)** The method according to claim 1, wherein the adhesive composition excludes solvents having boiling points above about 80°C.

- 6-7. **(Canceled)**

8. **(Original)** The method according to claim 1, wherein the solvent is selected from aliphatic and aromatic hydrocarbons, alcohols, ethers, ketones, esters, alcohol esters, ether alcohols, ether esters, ketone alcohols, ketone ethers, ketone esters, amides, nitriles, or a combination thereof.

9. **(Original)** The method according to claim 8, wherein the solvent is selected from acetone, isopropyl alcohol, dichloromethane, chloroform, tetrahydrofuran, ethyl acetate, methylethylketone or a combination thereof.

10. **(Original)** The method according to claim 9, wherein the solvent is acetone.

11. **(Original)** The method according to claim 1, wherein the conditions effective to remove the solvent from the adhesive comprise subjecting the adhesive to vacuum conditions.

12. **(Canceled)**

13. **(Original)** The method according to claim 1, wherein the manufacturing tool is formed from a material selected from thermoplastic or thermoset polymer, metal, ceramic, glass, or a combination thereof.

14. **(Original)** The method according to claim 12, wherein the adhesive composition is placed on the air-bearing surface side of said ceramic material.

15. **(Currently Amended)** In a method of manufacturing a slider for a hard disk drive, wherein an adhesive is used to bond a ceramic material to a manufacturing tool, the improvement which comprises employing a de-bondable adhesive composition consisting ~~essentially~~ of [[a]] **one or more** novolac resins and [[a]] **one or more** solvents, wherein the **one or more** solvents has a boiling point in the range of about 30°C to about 70°C.

16. **(Canceled)**

17. **(Original)** The method according to claim 15, wherein the solvent is selected from acetone, isopropyl alcohol, dichloromethane, chloroform, tetrahydrofuran, ethyl acetate, methylethylketone or a combination thereof.

18. **(Original)** The method according to claim 15, wherein the solvent is acetone.

19. **(Currently Amended)** A method of producing an adhesive composition having improved adhesive characteristics for use in bonding a ceramic material to a manufacturing tool comprising

adding [[a]] one or more solvents to [[a]] one or more novolac resins, wherein the one or more solvents has a boiling point in the range of about 30° C to about 70° C, in a manner sufficient to produce said adhesive composition with improved adhesive characteristics, wherein said composition consists essentially of [[the]] one or more novolac resins and [[the]] one or more solvents.

20. **(Original)** The method according to claim 19, wherein the resist adhesive resin is present in an amount of about 30 wt.% to about 80 wt.%.

21-23. **(Canceled)**

24. **(Original)** The method according to claim 19, wherein the solvent is selected from aliphatic and aromatic hydrocarbons, alcohols, ethers, ketones, esters, alcohol esters, ether alcohols, ether esters, ketone alcohols, ketone ethers, ketone esters, amides, nitriles, or a combination thereof.

25. **(Previously Presented)** The method according to claim 24, wherein the solvent is selected from acetone, dichloromethane, chloroform, tetrahydrofuran, methylethylketone or a combination thereof.

26. **(Original)** The method according to claim 25, wherein the solvent is acetone.

27. **(Withdrawn)** An adhesive composition for use in the manufacture of sliders for hard disk drive applications, comprising a resist adhesive resin and a solvent, wherein the solvent has a boiling point in the range of about 30°C to about 80°C.

28. **(Withdrawn)** The adhesive composition according to claim 27, wherein the resin is selected from novolac resins, poly(ethylene-co-vinylalcohol), poly(2-hydroxyethylmethacrylate), cellulose polymers, or a combination thereof.

29. **(Canceled).**

30. **(Withdrawn)** The adhesive composition according to claim 27, wherein the solvent is selected from aliphatic and aromatic hydrocarbons, alcohols, ethers, ketones, esters, alcohol esters, ether alcohols, ether esters, ketone alcohols, ketone ethers, ketone esters, amides, nitriles, or a combination thereof.

31. **(Withdrawn)** The method according to claim 30, wherein the solvent is selected from acetone, isopropyl alcohol, dichloromethane, chloroform, tetrahydrofuran, ethyl acetate, methylethylketone or a combination thereof.

32. **(Withdrawn)** The adhesive composition according to claim 30, wherein the solvent is acetone.

33. **(Withdrawn)** The adhesive composition according to claim 27, wherein the solvent has a boiling point in the range of about 30°C to about 70°C.

34. **(Withdrawn)** The adhesive composition according to claim 27, wherein the adhesive composition excludes solvents having boiling points above about 80°C.

35. **(Previously Presented)** The method of claim 19, wherein use of the improved adhesive composition results in an increase in yield of bonding efficiency over a resist composition that includes a novolac resin and a photosensitizer.

36. **(Previously Presented)** The method of claim 35, wherein the increase in yield is about 75% or more.